

ABSTRACT

The present invention addresses the problem of providing a resin molding die set which is capable of clamping without exerting excessive stress on a workpiece, regardless of the existence and magnitude of variations in a thickness of the workpiece. As means for solving the problem, a height of a workpiece support (37) is adjusted by a thickness-varying mechanism to match a thickness of a substrate (1), and a height of a cavity recess (32) is adjusted by a cavity-height-varying mechanism to match a height of a semiconductor chip (5) before a molding resin is supplied into a cavity.